Introduction to Evaluation Equipment for SiC Power Semiconductor & Power Module

2014/11/20 Disribution by S. Usui, Risoh Keisoku K.K.

Introduction to Evaluation Tester

- 1) 350°C Compact Thermal Shocker CHS350 for SiC power semiconductor Temp. Evaluation
- 2) 400°C High Temp. Constant Temp. Chamber HTC400: for SiC High Temp. Storage Test
- 3) Compact Constant Temp. Chamber RK-10207PL for large Element Power Module
- 4) 200A~2000A Large Current Source System for Power Cycle test of IGBT/FET module

Evaluation test for Power semiconductor RKKK (Risoh Keisoku K.K.) can help you

Test Item	Si module	SiC module	RKKK products support :	
	test condition	Test condition		
Thermal	-40°C60M	-40°C60M>> <mark>30M</mark>	Compact Thermal Shock Tester	
Shock test	+125°C60M	+250°C60M>> <mark>30M</mark>	CHS350	
Temp. Cycle	-40°C60M	-40°C60M>> <mark>30M</mark>		
500C、1000C	+125°C60M	+250°C60M>> <mark>30M</mark>	CHS350	
High Temp. Storage	Ta=+125°C、 1000H	Ta=+300°C、1000H	High Temp. Constant Temp. Chamber HTC400	
Low Temp S.	Ta=-40°C、1000H	Same as left	Low –Cost Constant Temp.& Humidity	
High Temp.	Tj=+125°C,	Tj=+250°C, Load, HTC400		
Bias	Load, 1000H	1000H		
Power Cycle	ΔTj=100°C, 5000C	ΔTj=200°C, 5000C	Large Current Source for Power Module PMPS	
HighTemp/ Humidity	+85°C85%	Same as left	TH series	

1996Established to develop/manufacture/sell of Measurement/Analysis/Control system suitable to Japan market.	ble to
2001Formal Agent of Intelligent Instrumentation Inc Developed/shipped OLED parameter test equipment & OLED Panel inspection equipment Developed/shipped Abnormal Sound Detection and Alarm system (NAMAS)	
2002 Developed/shipped OLED mother-glass Aging Large Current power supply Inspection system Developed/shipped Multi-channel Isolation Measurement system (LIMS)	tem
2003 Developed/shipped Compact Temperature Chamber for Light Emitting Device	
2004 Developed/shipped OLED Lifetime measurement system Developed/shipped Water-cooling Compact Temperature Chamber	
2005 Developed/shipped several kinds of OLED Inspection system and JIGUs Started selling Low-cost Constant Temperature Chamber	
2006Developed/shipped High-power LED Lifetime test system Developed/shipped Solar cell parameter test system	
2008Developed/shipped 1000 channel LED lifetime test system Developed/shipped Heat Cycle Lifetime test system LifeMAPS	
2009 Developed Compact Thermal Shocker (for SiC evaluation, -40 to +350 dC supported) backuped by Economy & Industry Ministry	kuped by
2010 Moved to current new-factory (Shibokuchi, Takatsu-ku, Kawasaki)	
2011 Developed/shipped 200A Power Module Large Current Power Supply system (PMPS)	
2012 Developed/shipped PMPS 500A system, IGBT driving signal system, 400°C High temp constant temp chamber, Developed/shipped -70°C compact temp chamber	nstant

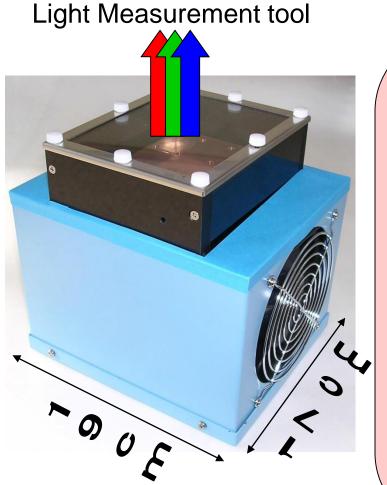
Feature of Risoh Keisoku K.K.

 Analog Measurement / Control Technology
 1987 World first LowCost 16bitADC Design / Develop / Mass Production (at BB)
 Multi-ch small current measurement, Large Current output

Compact space Constant Temp. Tech.
 Palm-top size Compact Temp. Chamber: -70°C
 Large size Temp. Chamber: 10~90°C
 Compact Thermal Shock Tester: -55°C~+350°C

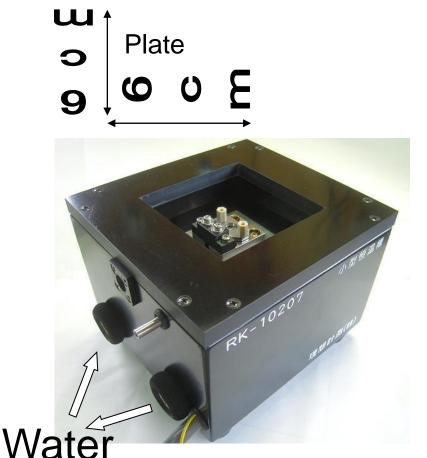
LargeCurrent Source Test Equipment
 Organic EL, Power LED Display Testers
 Power LED power / Temp. cycle Lifetime Tester
 IGBT module Evaluation Large Current Source ystem

Compact Temp. Chamber for Element Light Measurement tool RK-10207P



-40 to +150°C T-range Peltier thermal driving optimal for element Evaluation Top: Glass for Light Emitting Element (LED, OLED, LD etc.) **Direct Thermal Transfer** Speedy, Compact, Complete Air Cooling Palm-top size – on desk test **Utility**: Electric Power only No need for water / compressor

Water Cooling Compact Temp Chamber RK-10207



-70°C to +120°C T-range
Optimal for Car element
evaluation test
Direct Thermal Transfer
Speedy, Compact
Water cooling method
High Accuracy

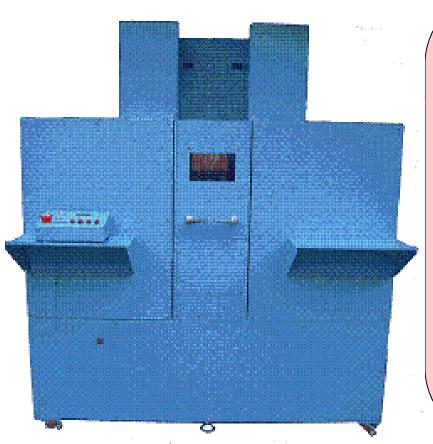
PV oriented Compact Temp. Chamber RK-10207P-120x120



-40 to +150°C T-range
 120x120mm Plate
 Optimal for Solar Cell Evaluation
 Direct Thermal Transfer
 Speedy, Compact
 Complete Air Cooling
 On-desk size

Small, High Performance, Large energy saving

Compact Thermal Shock Tester CHS350



-55 to +350°C T-range
 Test area size: 20x20x20cm³
 Optimal for SiC Evaluation
 & High Temp. Material test
 Thermal Shock test, Thermal Cycle test,

Speedy, Energy saving, Compact, Low cost

Large Reduction of CO₂
Discharge

Some parts of this CHS350 were developed with supports from 2009 Japan E/I Ministry, Yokohama National University, Kanagawa Industry & Technology Center and Kanagawa Academy of Science and Technology.

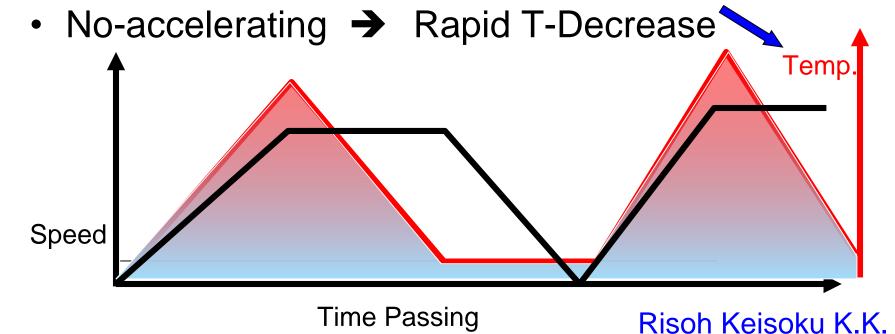
"Project Name: Development of Small Thermal Shock Tester for Temperature Characteristics Evaluation Test of Car Inverter Module etc."

Project Manager: S.Karasawa, H.Kobayashi. KAST General Research Representative: S.Usui, R.Ohira. RKKK Sub-General Research Representative: K.U, I.Shinohara. YNU Cooperator: T.Shinohara. KITC

- 2011 Win Incentive Prize at Kanagawa Industrial & Technology Dvelopment Award
- 2012 Win Kawasaki Entrepreneur Award

Environmental conditions of SiC Inverter for EV

- EV motor control << Mechatronical Integration >>
- Large Current, Large Power, Compact sizing, High Energy density
- Accelerating → Rapid T-Increase



Environmental conditions of SiC Inverter for EV

- Cars repeat always Accelerating / Decelerating
- SiC Inverter: Miniaturizing, Mechatronical Integration, Heat Concentration
- High / Low Temp. is repeated ultimately. (several 10s to several 100s in 24 hours) condition:
 - Used in IC-historically most hazardous temp environment
- High Temp. Durability → over than 300°C
- SiC Inverter, SiC semiconductor(module) need absolutely Environmental Durability Evaluation test
- Conventional Si-oriented Thermal Shocker is useless.
- Necessary for over 300°C supporting Thermal Shocker Conditions: Small, New method, Energy-saving, Speedy, Low Cost.

CHS350 Outline

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Compact Thermal Shocker for EV oriented Inverter module Temp. Character Evaluation

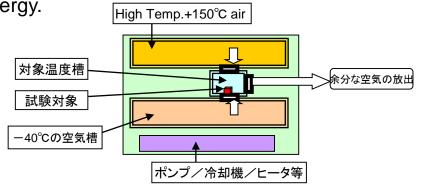
Thermal Shocker for Power module using new material such as SiC / GaN element with high durability, Compact & light weight, for purpose of additional energy saving of hybrid Car & EV.

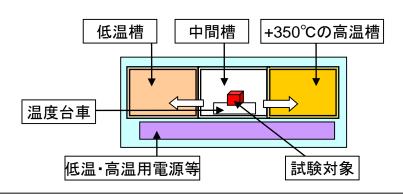
[Conventional technology]

In case of Air flow type, cycle test is repeated by 1) settle the target device in target temp. chamber, 2) generate high temp.air and low temp. air in 2 tanks, 3) flow in to target temp. chamber from each tank mutually. Since 2 air tanks are large and exchange large amount of high temp. air and low temp. air every cycle in to target chamber, it takes time and release airs every time into free air so that consumes large energy.

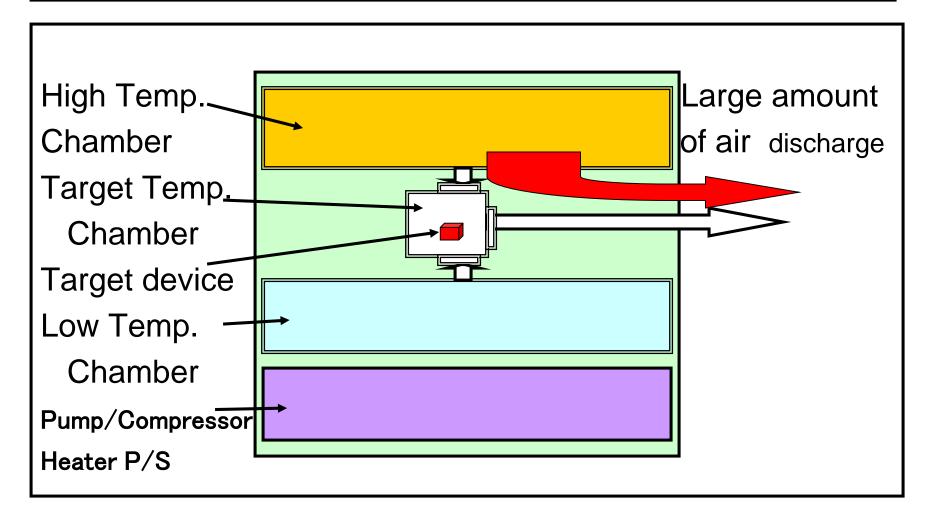
[New technology]

Settle the target device on the cart after generating low temp. of low temp. chamber with Peltier module and high temp. of high temp. chamber with heater. Moving the temp. cart between each chamber, Thermal shock cycle test is repeated. Eliminating air discharge saves large amount of energy and direct contact heat transfer method shortens time to the target temp. so that thermal chock cycle is performed with small size.

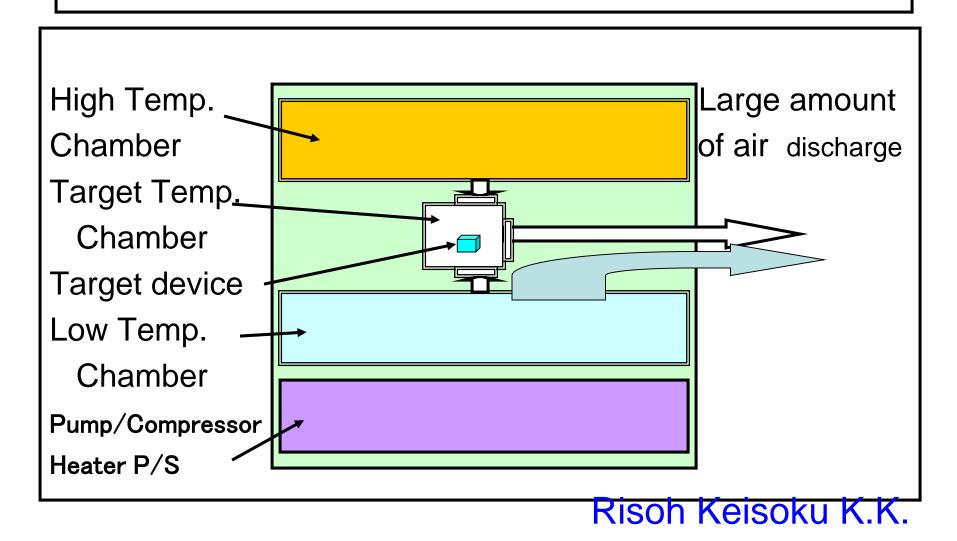




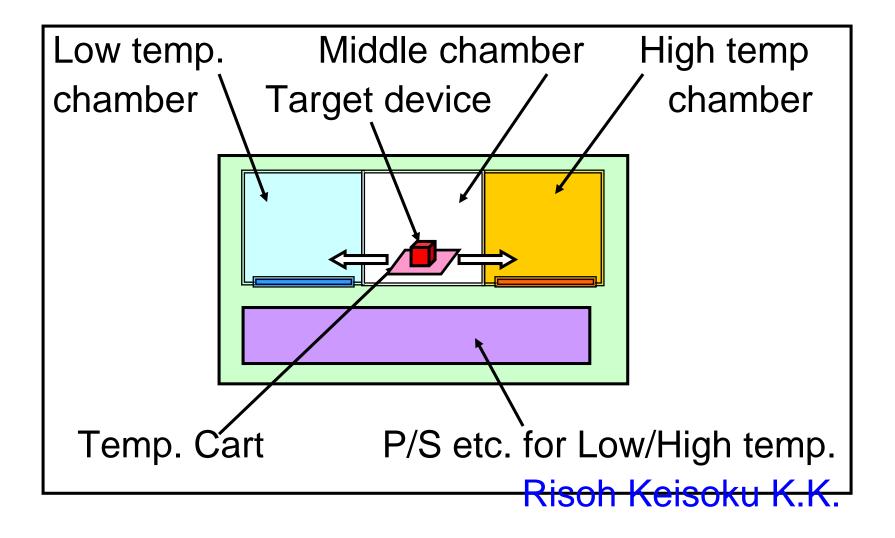
Conventional Air flow type Outline



Conventional Air flow type Outline

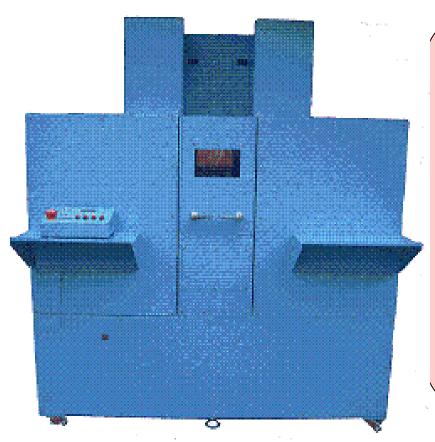


New Technology Outline



Small, High Performance, Large energy saving

Compact Thermal Shock Tester CHS350



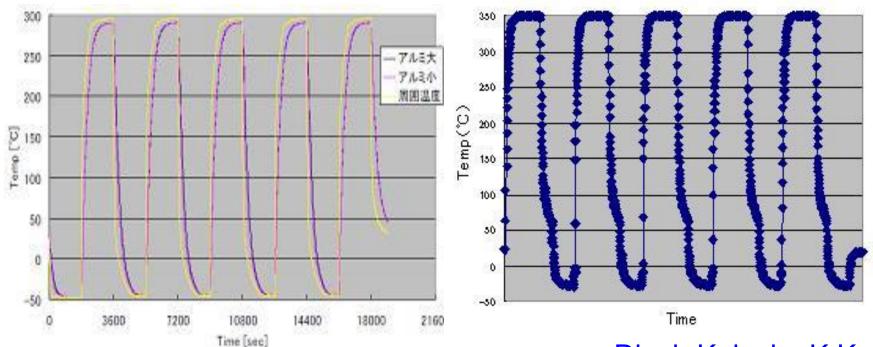
/-55 to +350°C T-range Test area size: 20x20x20cm³ Optimal for SiC Evaluation & High Temp. Material test Thermal Shock test, Thermal Cycle test, Speedy, Energy saving, Compact, Low cost Large Reduction of CO₂ Discharge

Temp. profile: Rapid & Accurate

- Test condition: Low Temp. 40°C, High Temp.+350°C
- Exposed period: 30 Minutes each
- Comparing data of Conventional machine and New designed CHS350

Conventional Air flow type

New method CHS350



Features

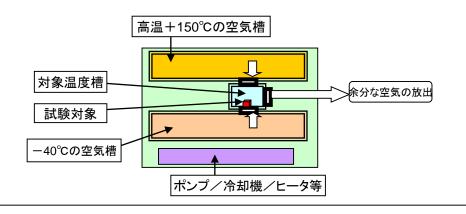
Risoh Keisoku K.K.

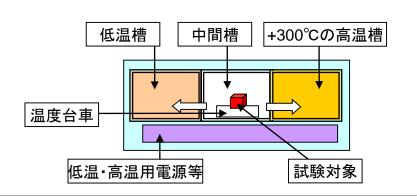
[Conventional Technology: Air flow method]

- 1. 2 large air tanks and 1 test chamber
- 2. Air Flow transfer
- 3. Air Exchanging method
- 4. Large amount energy
- 5. Large Temp. error
- 6. Needs Time
- 7. Large and Heavy

[New Technology: Direct Heat Transfer method]

- 1. 3 small chambers
- 2. Metal Direct Contact
- 3. Direct Heat transfer method
- 4. Small amount energy: Ecology
- 5. High accurate Temp.
- 6. Short Time
- 7. Small and Light





Item	Conventional Technology: Air flow Thermal Shocker	New Direct Heat Transfer method Thermal Shocker
Power & Running Cost	25kW/h 14M Jyen / 5 years	2.5kW/h (1/10 of left) 1.4M Jyen / 5 years
Temp. Range	High T.: +50 to +250°C Low T.: -10 to -70°C	High T.: +50 to +350°C Low T.: +20 to -55°C
T-Rising speed	RT→+250°C: 40M	RT→+300°C: 10M
Utility	Chilled water & High Pressure air	Chilled water & High Pressure air
Size	388Wx196H(+6)x 177D cm	160Wx135H(+40)x 60D cm
Weight	1000kg over	280kg

Small, High Performance, Large energy saving Compact Thermal Shocker CHS350

< for SiC Semiconductor & Module of EV & PV > Ratio to convention 1/10 super energy saved

<< Thermal Shock test >>

- CO₂ Discharge : Large reduction
- Super Compact 1700cm³
- •5 year running cost of the conventiona allows you to buy CHS350
- Innovational low cost



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400°C High Temp oriented Constant Temp Chamber HTC400



RT to +400°C T-range SiC Power Semiconductor High Temp Storage test, High Temp Bias test Inner size: 30x30x30 cm³ Direct Heat Transfer method: $+/- 1.0^{\circ}C (at 400^{\circ}C)$ Small outside size: 60Wx69Dx70Hcm³

Constant Temp Chamber HTC400 Inner view



HTC400 Temp. Accuracy

Designated Temperature	Temp. Accuracy of Temp. Metal Plate
20°C	+0.3/-0.3
80°C	+0.2/-0.2
100°C	+0.2/-0.2
200°C	+0.2/-0.2
300°C	+0.3/-0.3
400°C	+0.4/-0.4

Large Element oriented Constant Temp. Chamber RK-10207PL





+10 to +90°C T-range
 Optimal to Largest
 Element Evaluation
 Direct Heat Transfer
 Speedy, Air cooling type
 (Water cooling: option)
 High Accuracy &
 Low cost

OLED Aging Multi-ch Large Current Source P/S RK-10248

96 channel Aging Current Source



Current: 2A/ch

Compliance Voltage: 24V

Ch number: 96ch

Optimal for OLED mother

glass aging

For Light Emitting Element (LED, LD, etc.)

Cycle Power Lifetime tester with integration to Compact Temp. Chamber

Cycle Lifetime test Equipment LifeMAPS

LifeMAPS



Current: 50mA/ch

Compliance Voltage:

120/80V

Ch number: 20ch

Temp. range:

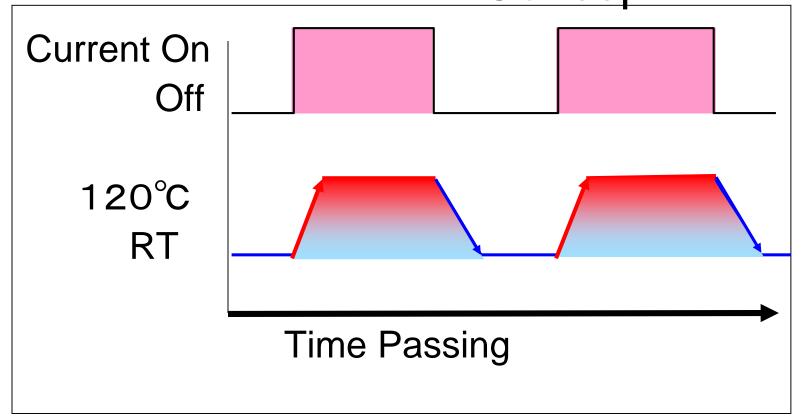
+10°C to +150°C

Integrated System of Compact Tem. Chamber & Multi-ch current power source

For Light Emitting Element: Power LED, Laser Diode, etc.

1000 ch test with 50 sets

Cycle Lifetime test Equipment LifeMAPS Concept

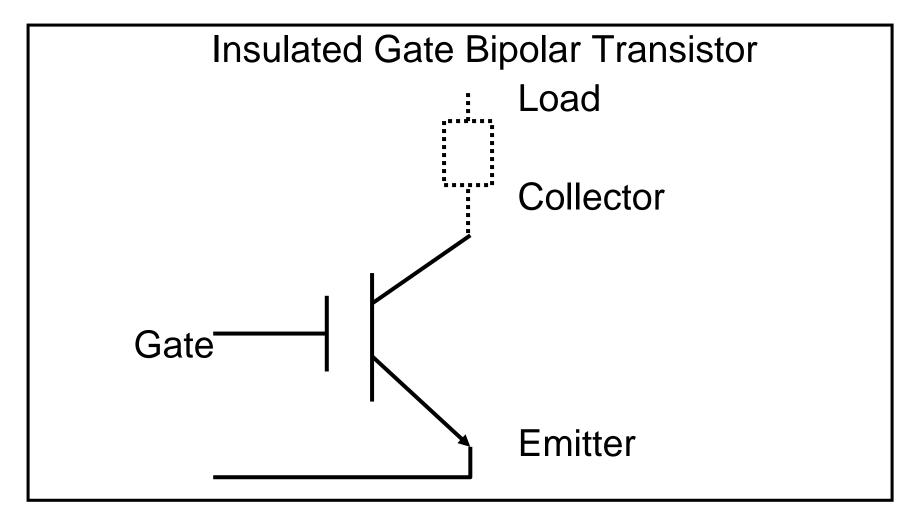


Heat Cycle simultaneous to LED power On/Off

Cycle Lifetime test Equipment LifeMAPS 50 sets → 1000ch



Power Module IGBT



Large Current Cource System for Power Cycle test of IGBT/FET module RK-PMPS200/500



-0 TO 3 > 0 O N



-0 CO 3 ≯000u

Current Source:

for IGBT Evaluation

Max Current: by model

200A, 500A, 800A, 1000A, 2000A

Current Control:

by Risoh Kiesoku Hybrid-IC

Cooling method : Complete Air cooling

Control signal: Gate signal output Measurement signals:

Vce, Vf, Temp. inputs

Alarm signal: Limit detection

Evaluation Tester for Power Semiconductor & Power module

- 1) 350°C Compact Thermal Shocker CHS350 for SiC power semiconductor Temp. Evaluation
- 2) 400°C High Temp. Constant Temp. Chamber HTC400: for SiC High Temp. Storage Test
- 3) Compact Constant Temp. Chamber RK-10207PL for large Element Power Module
- 4) 200A~2000A Large Current Source System for Power Cycle test of IGBT/FET module PMPS200/500/1000/2000
- 5) Custom System to satisfy user specs & needs